



PATENT

Attorney Docket No. MTI-31471

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1-1603
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Guy Perry
Serial No. : 09/927,675
Filing Date : August 10, 2001
For : Bond Pad Structure Comprising Multiple Bond Pads with Metal Overlap
Group Art Unit : 2815
Examiner : CHU, Chris C.
Confirmation : 6524

CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10

I hereby certify that, on the date shown below, this correspondence is being:

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37 CFR 1.8(a)

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TECHNOLOGY CENTER 2800RESPONSE TO RESTRICTION REQUIREMENT
AND PRELIMINARY AMENDMENT

Sir:

Restriction Requirement. In response to the Examiner's requirement for an election of the claims, mailed December 17, 2003, in the above-identified patent application, Applicant elects Group I, Claims 1-34 and 50-65, drawn to a bond pad structure, and to an integrated circuit die, with traverse.

Preliminary Amendment. Prior to substantive examination, Applicant requests that the following amendments be made to the above-referenced application.

01/13/2003 M6EBREM1 00000098 09927675

01 FC:1201 672.00 DP
02 FC:1202 144.00 DP

MKE/815641.1